

Automotive Power MOSFET Module

NXV08H350XT1

Features

- 2 Phase MOSFET Module At Customer Side this Module Can Be Used as 1/2 Bridge MOSFET Module by Combining 2 Phase Out Power Terminals
- Electrically Isolated DBC Substrate for Low Rthjc
- Compact Design for Low Total Module Resistance
- Module Serialization for Full Traceability
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ORDERING INFORMATION

Part Number	Package	Pb–Free and RoHS Compliant	Operating Ambient Temperature Range	Packing Method	
NXV08H350XT1	APM17-MDC	yes	−40~125°C	Tube	

Pin Configuration



Figure 1. Pin Configuration

Block Diagram



Figure 2. Schematic

Flammability Information

All materials present in the power module meet UL flammability rating class 94V-0.

Compliance to RoHS Directives

The power module is 100% lead free and RoHS compliant 2000/53/C directive.

Solder

Solder used is a lead free SnAgCu alloy.

Base of the leads, at the interface with the package body should not be exposed to more than 200°C during mounting on the PCB, this to prevent the remelt of the solder joints.

Symbol	Parameter	Max.	Unit
VDS(Q1~Q4)	Drain-to-Source Voltage	80	V
VGS(Q1~Q4)	Gate-to-Source Voltage	±20	V
EAS(Q1~Q4)	Single Pulse Avalanche Energy (Note 1)	1946	mJ
TJ	Maximum Junction Temperature	175	°C
T _{STG}	Storage Temperature	125	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Starting $T_J = 25^{\circ}$ C, L = 0.47 mH, $I_{AS} = 91$ A, $V_{DD} = 72$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.

ISOLATION VOLTAGE (Isolation voltage between the Base plate and to control pins or power terminals.)

Test	Test Condition	Test Time	Min	Max	Unit	
Leakage @ Isolation Voltage (Hi-Pot)	VAC = 3 kV	Time = 1 s				

TYPICAL CHARACTERISTICS

10K								1000							
								900							
1K								800							
400								600							
100															
								400							
10								300							
10								200							
1								0							
0.001	0.01	0.1	1	10	100	1K	10K	0	0.2	0.4	0.6	0.8	1.0	1.2	1.4
		t _{AV} , TIM	E IN AVA	ALANCH	IE (ms)				V _{DS} ,	DRAIN-	-TO-SO	URCE V	OLTAGE	E (V)	
F	igure 3	3. Uncla	amped Capal	Induct bility	ive Swi	tching	J		Figu	ire 4. Sa	aturatio	on Chai	acteris	tics	

V_{GS}, GATE-TO-SOURCE VOLTAGE (V) Figure 5. R_{DSON} vs. Gate Voltage T_J, JUNCTION TEMPERATURE (°C) Figure 6. R_{DSON} vs. Temperature





T_C, CASE TEMPERATURE (°C)



Figure 14. Flatness Measurement Position

MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Test Conditions	Min	Тур	Max	Units
Device Flatness	Refer to the package dimensions	0	-	150	um
Mounting Torque	Mounting screw: M3, recommended 0.7 N•m	0.4	-	1.4 (Note 5)	N∙m
Weight		-	23.6	_	g

5. Max Torque rating can be different by the type of screw, such as the screw head diameter, use or without use of Washer. In case of special screw mounting method is applied, contact **onsemi** for the proper information of mounting condition.



1

APM17-MDC CASE MODHH ISSUE C

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